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Abstract



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Methods for producing a semiconductor component and semiconductor component.

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Title of the invention: Methods for producing a semiconductor component, semiconductor component

10 The invention relates to methods for producing a semiconductor component (1) provided for mounting on a printed circuit board, the semiconductor component comprising a housing (8), which housing (8) surrounds at least one semiconductor chip (3) formed in planar fashion at least partially with a rear side area (81)
15 and/or side areas (82), the semiconductor chip being assigned electrical contacts (5) by means of which an electrical connection to electrodes or electrode areas provided on the printed circuit board is to be produced, which electrical contacts (5) are
20 electrically connected to electrical contact areas (32) on the front side (33) of the semiconductor chip (3), which electrical contact areas are situated together within a significantly smaller contact-making region (31) than the total area of the front side (33).

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(Figure 1)